



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-10-31
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH1R06AFY	BA3E*V09B8AN	A	Z6IA	2017-10-31
Amount		UoM	Unit type	ST ECOPACK Grade
26.40		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFF	1.75X4.7X0.98	NA	flat	
Comment	Package: SOD128-FLAT NEP			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Die	265
Lead	2.67	Soft solder	101061

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BA3E*V0988AN					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.615	mg	supplier	die	Silicon (Si)	7440-21-3		0.486	mg	790244	18409
				supplier	metallization	Aluminium (Al)	7429-90-5		0.112	mg	182114	4242
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	14634	341
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1626	38
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.007	mg	11382	265
Leadframe & Clip	Copper and its alloys	12.263	mg	supplier	alloy	Copper (Cu)	7440-50-8		12.184	mg	993558	461515
				supplier	alloy	Iron (Fe)	7439-89-6		0.072	mg	5871	2727
				supplier	alloy	Iron Phosphide (Fe2P)	1310-43-6		0.004	mg	326	152
				supplier	alloy	Zinc (Zn)	7440-66-6		0.003	mg	245	114
Die Attach	Other organic materials	2.809	mg	JIG R	soft solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.668	mg	949804	101061
				supplier	soft solder	Tin (Sn)	7440-31-5		0.141	mg	50196	5341
Encapsulation	Other organic materials	10.411	mg	supplier	mold compound	Silica	60676-86-0		6.373	mg	612141	241402
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		1.715	mg	164730	64962
				supplier	mold compound	Metal hydroxide	21645-51-2		1.373	mg	131880	52008
				supplier	mold compound	Phenol resin	9003-35-4		0.915	mg	87888	34659
Connection coating	Solder	0.302	mg	supplier	mold compound	carbon black	1333-86-4		0.035	mg	3361	1325
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.302	mg	1000000	11439